Molex FiT Families Power Connectors

Reflow capable headers reduce processing requirements and reduce costs

Molex's FiT families feature reflow capable headers molded in liquid crystal polymers (LCP) that can withstand +260°C and higher during reflow processing. These connectors are designed to be automated assembly–ready, which can optimize installation times, reduce human error and save significant processing costs. With secondary wave solder processes being used less often or eliminated, reflow capable connectors like those offered in the FiT families meet processing requirements that can result in significant cost savings.

AVOID DAMAGE ASSOCIATED WITH REFLOW PROCESSES ON NON-REFLOW COMPONENTS

UNDAMAGED IN REFLOW PROCESS

DAMAGED IN REFLOW PROCESS

The FiT families power connectors include Mega-Fit®, Mini-Fit®, Ultra-Fit™, Micro-Fit 3.0™ and the Nano-Fit™ product lines, all of which are readily available in various circuit sizes and plating options.

www.molex.com/FIT

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